

GB10281N

Powerful HGX H200 8-GPU AI Server to Bring the Next-level GPU Performance



Powerful HGX H200 8-GPU AI Server

Engineered for generative AI and high-performance computing, the AI server harnesses the power of eight H200 Tensor Core GPUs, connected via ultra-fast NVIDIA NVLink, to deliver 32 petaflops of AI performance. With enhanced HBM memory, the system ensures faster data transfer and minimizes bottlenecks, accelerating workflows and driving breakthroughs in AI and HPC.

Application

- Generative AI
- Large Language Model (LLM)
- AI and Machine Learning
- High Performance Computing

Innovative Disaggregated Approach

The AI server can pair with an x86-based CPU head node server to create a powerful and unified AI solution. This disaggregated GPU and CPU approach enhances flexibility, enabling you to select the head node server that best suits your needs. (Ingrasys head node solution: SV2121A/SV2121I)

High Expansion Capability

Adopting a one-GPU-to-one-NIC topology, the powerful server offers high expansion capability by accommodating 8 NICs, which enables fast interconnections between GPUs within a GPU cluster. Its two-layer design features easy scalability up to 32 NVMe drives and enhances thermal efficiency, delivering unprecedented performance and agility.



NVIDIA HGX H200 8-GPU



32 x U.2 NVMe Drive Bays



Up to 20 PCIe 5.0 x16 Slots



5+5 Redundancy, Platinum Level



10U Rackmount

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Specifications



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Supported GPU

NVIDIA HGX H200 8-GPU



Expansion Slots

20 x PCIe 5.0 x16 Slots



Storage

32 x Hot-swap U.2 NVMe Drive Bays



Front Panel

1 x Power LED, 1 x UID LED, 1 x Attention LED,
1 x 1GbE/RJ45 Management Port
1 x RJ45 Console Port



Form Factor

10U Rackmount
(4U IOB Sled with 4U GPU Sled)



Chassis Dimensions (H x W x D)

17.3" x 20.0" x 37.3" /
440.5mm x 508.0mm x 948.8mm



Management

1 x ASPEED AST2600



Power Supply

5+5 Redundant 3000W Platinum Power Supplies



Fans

24 x 80*80mm for N+1 Cooling Redundancy



Certification

CE/FCC/RCM/BSMI/UL/
IECEE CB



Operating Temperature

10°C to 35°C (50°F to 95°F)

Non-operating Temperature

-40°C to 60°C (-40°F to 140°F)

Operating Relative Humidity

8% to 85%RH

Non-operating Relative Humidity

5% to 95%RH



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